

Operation: SMT & Push Lever MINI-SIM 工业级识别卡座 (托盘卡托)



LTEM NO.: SIM-021 (Industrial)
(33.0L × 25.0W × 3.0H & MEMORY-CARD-SOCKETS)

MINI SIM SOCKETS

Technical parameter

表面貼裝 SMT

PROJECT	LEVEL	A[better product]	B[average product]
		Contact Rating	
Electrical Properties	Initial Contact Resistance	50mΩ max.	60mΩ max.
	Insulation Resistance	100MΩ min.500V DC	Skey/PD: 100MΩ min.300V DC
	Withstand Voltage	500V AC for 1 minute	350 V AC for 1 minut
Durable Performance	There No Load	10,000 Cycles	8,500 Cycles
	Rated Load	8,500 Cycles	6,500 Cycles
	Storage temp.	-40℃~+85℃(Operating Temp:)	

正向導入 LATERAL

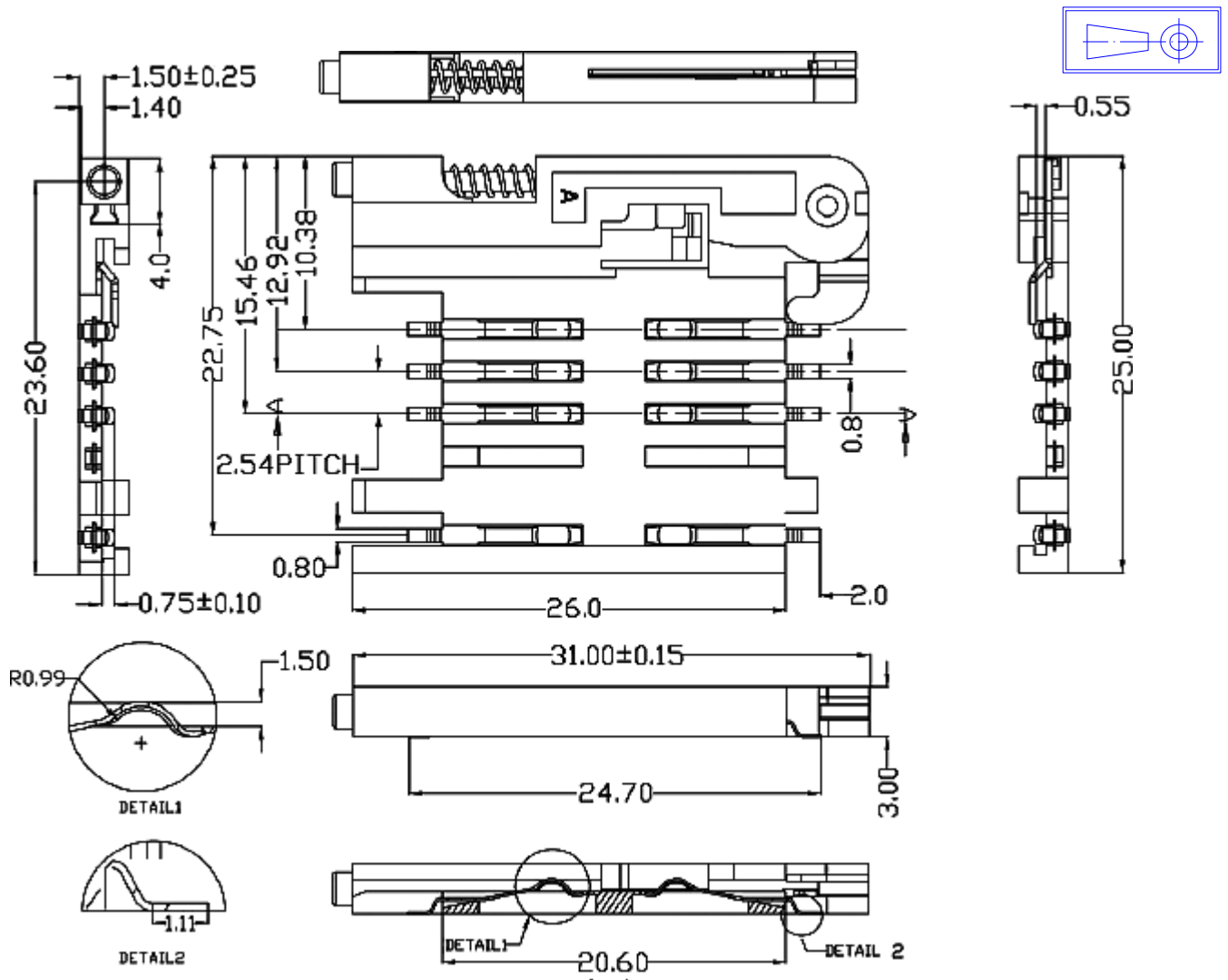
精密部品 NICETY

可靠 STABILIZE

適合環保 RoHS

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Unit:mm



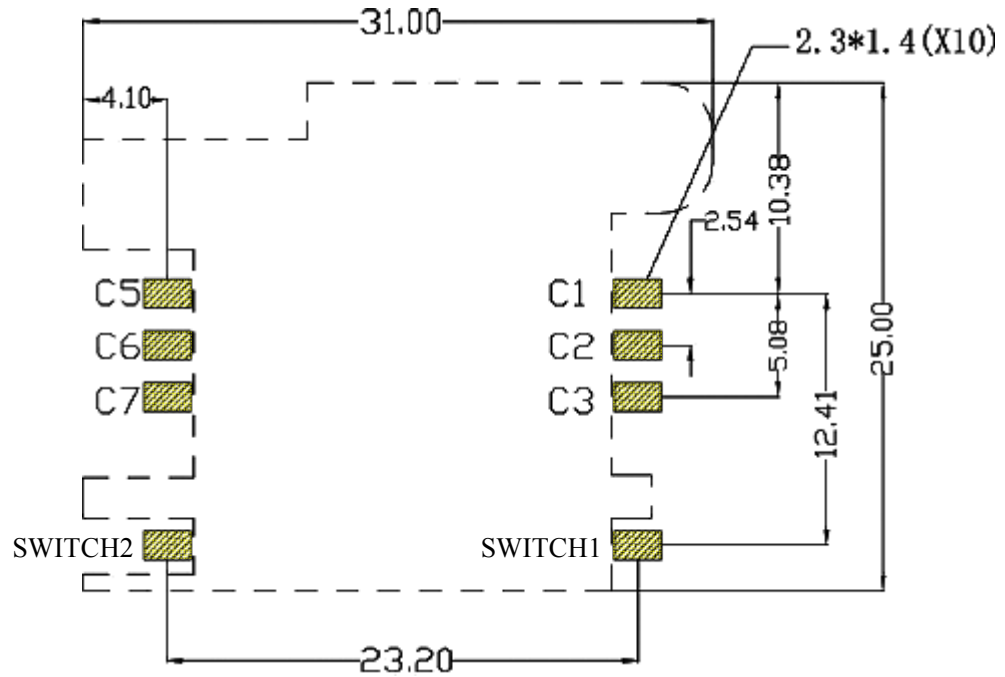
Operating Force

Inward
Exiting

8.0~12.0N. (1N.=100Gram Force)
12.5N. [±200gf]

Solder-ability (Max.)

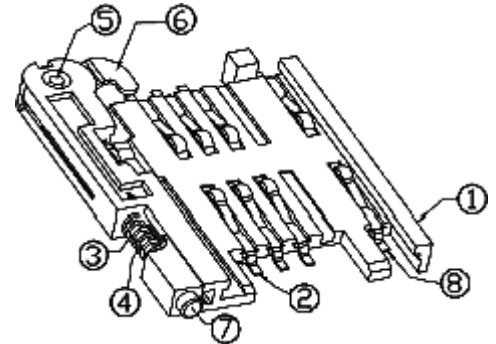
IR Reflow: 250°C, 3sec. Manual: 350°C, 3sec.



Pin definition

Material declaration

No.	NAME	MATERIAL	PLATING
①	BASE 基座	LCP (Black)耐高温塑胶	-
②	DATA CONTACT 接触端子	C5210 磷青铜 (镍 50 μ"基镀金 15 μ")	6-gold-plating
③	SPRING 弹簧	SUS301 不锈钢	-
④	PUSH ROD 推杆	Q345 锰钢	-
⑤	ROLLER 旋转轴	Brass 黄铜 (□1.1mm)	-
⑥	TOGGLE LEVER 肘节杆	SUS301 不锈钢 直径 t=0.40	-
⑦	HANDLE 操作柄	PPS/LCP 塑胶	-
⑧	SWITCH PIN 开关端子	C5210 磷青铜 (镍 50 μ"基镀金 15 μ")	gold-plating



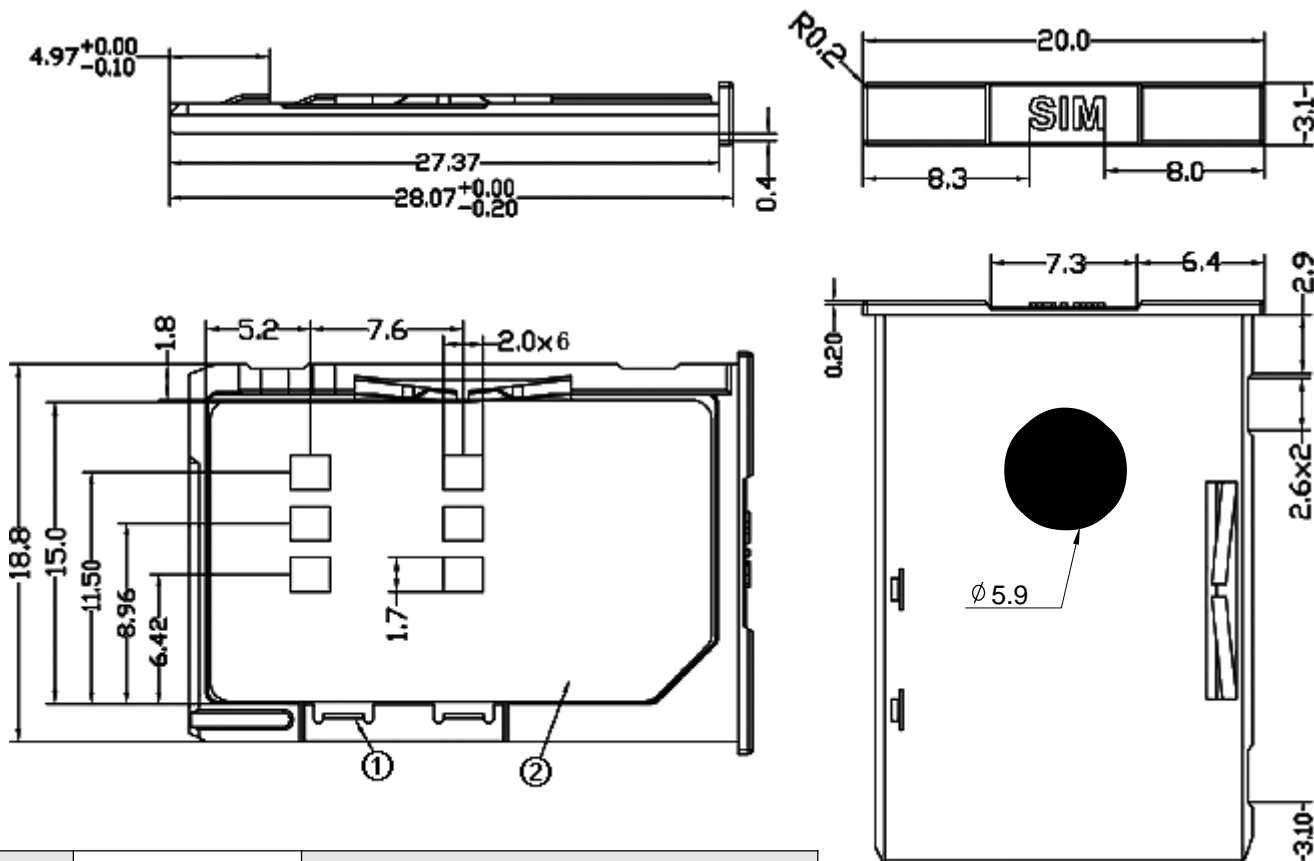
Pin No.	Pin NAME	Type	Description
C ①	卡电源	1	VCC
C ②	复位	1	RST
C ③	时钟	1	CLK
C ⑤	接地	1	GND
C ⑥	Vpp	1	VPP
C ⑦	输入/输出	1	I/O
SWITCH1	CD 组合开关	1	Cd switch1
SWITCH2	CD 组合开关	1	Cd switch2

本品不屬於危害性廢棄物,須丟棄時可以委託回收商予以回收再生處理。Products do not belong to hazardous waste, When waste can recycling processing

運送時本產品不要直接與水、酸鹼性化學物質接觸,或放置於含有以上氣體環境中,並且需要注意會有滑落、側翻的危險發生; 運輸過程中不能有碰撞或者擠壓,須保證溫度與濕度適中 [常溫 25°C, 濕度在 50°C 以內], 不可導致材料變形或氧化。

注記 NOTICE

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No.	NAME	MATERIAL
①	卡托端子 TERMINAL	PHOSPHOR BROMZE(T=0.15mm)磷青銅
②	卡托本体 COVER	PBT+30%G.F (Black)塑膠

SPECIFIED TOLERANCES UNLESS OTHERWISE



DECIMALS	ANGLES
X. :±0.50	X :±3°
X.X :±0.35	X.X :±1°
X.XX :±0.15	

■ 回流方式的参考举例

Please practice according to below condition:

- (1) Preheat :150 °C 90-120s
- (2) Soldering heat : 250 °C Max 3S.
- (3) Immersion depth: Up to the surface of the board

